

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ronald Eisele</td> <td>12/06/2011</td> </tr> </tbody> </table>		Name	Execution Date	Ronald Eisele	12/06/2011				
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<table border="1"> <tr> <td>Name:</td> <td>Danfoss Silicon Power GmbH</td> </tr> <tr> <td>Street Address:</td> <td>Heinrich-Hertz-Str. 2</td> </tr> <tr> <td>City:</td> <td>D-24837 Schleswig</td> </tr> <tr> <td>State/Country:</td> <td>GERMANY</td> </tr> </table>		Name:	Danfoss Silicon Power GmbH	Street Address:	Heinrich-Hertz-Str. 2	City:	D-24837 Schleswig	State/Country:	GERMANY
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CORRESPONDENCE DATA									
<p>Fax Number: 8605270464 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 8605495290 Email: carpenter@ip-lawyers.com Correspondent Name: M. Cunningham McCormick Paudling Huber Address Line 1: 185 Asylum St Address Line 4: Hartford, CONNECTICUT 06103</p>									
ATTORNEY DOCKET NUMBER:	6495-0580WOUS								
NAME OF SUBMITTER:	Marina F. Cunningham								
Signature:	/Marina F. Cunningham/								
Date:	07/17/2013								
Total Attachments: 1 source=Assignment#page1.tif									

OP \$40.00 13883348

ASSIGNMENT

THIS INSTRUMENT OF ASSIGNMENT WITNESSETH THAT:

WHEREAS, I,

Ronald Eisele
Faulstrasse 21
D-24229 Surendorf
Germany

have invented improvements in

POWER SEMICONDUCTOR MODULE WITH METHOD FOR MANUFACTURING A
SINTERED POWER SEMICONDUCTOR MODULE


for which we filed an application for Letters Patent of the United States, and

WHEREAS, Danfoss Silicon Power GmbH, a German corporation, having a place of business at Heinrich-Hertz-Str. 2, D-24837 Schleswig, Germany, is desirous of acquiring an interest in said invention, said application and the Letters Patent to be issued therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for and in consideration of the sum of ONE DOLLAR to each in hand paid and other good and valuable consideration, the receipt whereof is hereby acknowledged, we have sold, assigned and set over, and do hereby sell, assign and set over to said corporation, its successors or assigns, the entire right, title and interest to and in said invention in the United States and in all countries foreign to the United States, said United States application for Letters Patent therefor and the Letters Patent when issued; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue the Letters Patent based upon said application to said corporation as the assignees of our entire right, title and interest to and in the same, for the sole use and behoof of said corporation, its successors or assigns.

And we also hereby covenant and agree to sign all proper papers including divisional and other applications for patents and assignments thereof in the United States and application for patents and assignments in all foreign countries, and to execute all rightful oaths and to take any other proper action that may in the judgment of the said corporation be necessary for securing thereto full rights to said invention, all of the foregoing to be at the expense of said corporation.

IN TESTIMONY WHEREOF, I have hereunto set my hand this 6 day of December, 2011.



Ronald Eisele